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Claims:

- 1. A method for precisely aligning at least two parts of an electronic device, each part of said electronic device comprising at least one pad, said at least one pad of a first of said at least two parts being aligned with said at least one pad of a second of said at least two parts when said first and second parts are aligned, forming at least one pair of pads, said method comprising the steps of:
- deposing glue on said at least one pad of a first part of said at least two parts,
 - aligning approximately said second part to said first part, and,
 - lying said second part on said first part.
- 2. The method of claim 1 further comprising the step of 15 reducing said glue to a liquid state.
 - 3. The method of either claim 1 or claim 2 wherein the pads of said at least one pair of pads are of different sizes.
- 4. The method according to any one of claims 1 to 3 20 wherein the shape of said at least one pad of one of said at least two parts is rectangular.
 - **5.** The method of any one of claims 1 to 4 wherein the shape of at least two pads of one of said at least two parts are rectangular and wherein the angle formed by their longer edges is approximately equal to 90°.

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- **6.** The method according to any one of claims 1 to 5 wherein the shape of said at least one pad of one of said at least two parts is annular.
- 7. The method of any one of the previous claims wherein5 the shapes of the pads of a same pair of pads are similar.
 - 8. The method of any one of the previous claims wherein at least one of said at least two parts further comprises at least one passive stopper.
- 9. The method of any one of the previous claims wherein at 10 least one of said at least two parts further comprises three non-colinear passive stoppers.
 - 10. The method according to any one of claims 1 to 9 wherein said glue is electrically conductive.
- 11. The method according to any one of claims 1 to 9
 15 wherein said glue is made of soldering alloy.
 - 12. The method of any one of claims 1 to 11 wherein the volume of said liquid glue is predetermined according to the shapes of the pads of said at least one pair of pads.
- 13. The method of any one of the previous claims wherein 20 the volume of said liquid glue is predetermined according to the distance that must be set between said first and second parts.

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- 14. The method of any one of the previous claims further comprising the step of applying a mechanical force on one of said first and second parts, said force being approximately orthogonal to the pads of said at least one pair of pads.
- 5 **15.** The method of any one of the previous claims further comprising the step of,
 - hardening said liquid glue.
 - 16. The method of claim 15 wherein said step of hardening said glue comprises a cooling step.